

Product/Process Change Notice - PCN 11_0274 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: ADF4218L Wafer Fabrication Transfer

Publication Date: 02-Nov-2011

Effectivity Date: 31-Jan-2012 (the earliest date that a customer could expect to receive changed material)

Revision Description:

Initial Release

Description Of Change

Wafer fabrication of the ADF4218L is being transferred from the 6" 0.35um BiCMOS process to 8" 0.35um BiCMOS process in the Analog Devices, Limerick, Ireland.

Reason For Change

Increased wafer fabrication capacity.

Impact of the change (positive or negative) on fit, form, function & reliability

This transfer will not affect the form, fit, function, quality or reliability of the ADF4218L.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_11_0274_Rev_- ADI_PCN_11_0274_Rev_- ADF4218L_Qualification_Data.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative							
Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan: Rest of Asia:	PCN_Japan@analog.com PCN_ROA@analog.com		

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (3)					
ADF4218L / ADF4218LBRUZ	ADF4218L / ADF4218LBRUZ-REEL	ADF4218L / ADF4218LBRUZ-REEL7			

Appendix B - Revision History							
Rev	Publish Date	Rev Description					
Rev	02-Nov-2011	Initial Release					

Docld:1752 Parent Docld:None Layout Rev.6